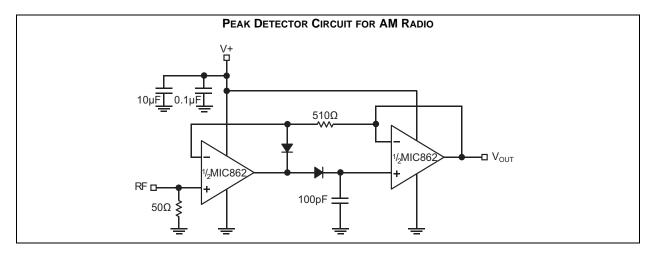
Typical Application Schematic



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Supply Voltage (V_{V+} to V_{V-})	+6.0V
Differential Input Voltage (V _{IN+} to V _{IN-}) (Note 1)	+6.0V
Input Voltage (V _{IN+} to V _{IN-})	V _{V+} + 0.3V, V _V _ – 0.3V
Output Short-Circuit Current Duration	Indefinite
ESD Rating (Note 2)	ESD Sensitive
- · · ·	

Operating Ratings ‡

Supply Voltage (V+ to V-)

† Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

‡ Notice: The device is not guaranteed to function outside the operating ratings.

- **Note 1:** Exceeding the maximum differential input voltage will damage the input stage and degrade performance (in particular, input bias current is likely to increase).
 - 2: Devices are ESD sensitive. Handling precautions are recommended. Human body model, 1.5 k Ω in series with 100 pF.

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TABLE 1-1: ELECTRICAL CHARACTERISTICS

Electrical Characteristics: V+ = +2V, V- = 0V, V_{CM} = V+/2; R_L = 500 k Ω to V+/2; -40°C ≤ T_A ≤ +85°C unless otherwise noted.

otherwise noted.						
Parameters	Symbol	Min.	Тур.	Max.	Units	Conditions
		-6	0.1	6		—
Input Offset Voltage		-5	0.1	5	mV	$T_A = +25^{\circ}C$
Differential Offset Voltage	V _{OS}	—	0.5	_	mV	—
Input Offset Voltage Temperature Coefficient		_	6		μV/°C	_
Input Bias Current	Ι _Β	_	10	_	pА	_
Input Offset Current	I _{OS}	_	5		pА	_
Input Voltage Range (from V–)	V _{CM}	0.5	1	_	V	CMRR > 50 dB
Common-Mode Rejection Ratio	CMRR	45	75	—	dB	0V < V _{CM} < 1V
Power Supply Rejection Ratio	PSRR	50	78	_	dB	Supply voltage change of 2V to 2.7V.
		66	74	_		R _L = 5 kΩ, V _{OUT} = 1.4 V _{PP}
Large-Signal Voltage Gain	A _{VOL}	75	89		dB	R _L = 100 kΩ, V _{OUT} = 1.4 V _{PP}
Voltage Call		85	100			R _L = 500 kΩ, V _{OUT} = 1.4 V _{PP}
Maximum Output		V+ – 80 mV	V+ – 55 mV	_	V	$R_L = 5 k\Omega$
Voltage Swing		V+ – 3 mV	V+ – 1.4 mV	_		R _L = 500 kΩ
Minimum Output	V _{OUT}	_	V– + 14 mV	V– + 20 mV	V	$R_L = 5 k\Omega$
Voltage Swing		_	V– + 0.85 mV	V– + 3 mV		R _L = 500 kΩ
Gain-Bandwidth Product	GBW	—	2.1		MHz	$R_L = 20 \text{ k}\Omega, C_L = 2 \text{ pF, } A_V = 11$
Phase Margin	PM	_	57		0	R_L = 20 kΩ, C_L = 2 pF, A_V = 11
–3 dB Bandwidth	BW		4.2		MHz	R_L = 1 MΩ, C_L = 2 pF, A_V = 1
Slew Rate	SR	_	2	_	V/µs	R_L = 1 MΩ, C_L = 2 pF, A_V = 1, Positive Slew Rate = 1.5 V/µs
Short-Circuit Output		1.8	2.6			Source
Current	I _{SC}	1.5	2.2	_	mA	Sink
Supply Current (per Op Amp)	۱ _S	_	27	43	μA	No Load
Channel-to- Channel Crosstalk		_	-100		dB	Note 1

Note 1: DC signal referenced to input. Refer to the Typical Performance Curves section's AC performance graphs.

TABLE 1-2: ELECTRICAL CHARACTERISTICS

Electrical Character otherwise noted.	ristics: V+	= +2.7V, V- =	= 0V, V _{CM} :	= V+/2; R _L = 50	00 kΩ to V+	$T/2$; $-40^{\circ}C \le T_A \le +85^{\circ}C$ unless

Parameters	Symbol	Min.	Тур.	Max.	Units	Conditions
		-6	0.1	6	- mV	—
Input Offset Voltage		-5	0.1	5	mv	$T_A = +25^{\circ}C$
Differential Offset Voltage	V _{OS}	_	0.5	_	mV	_
Input Offset Voltage Temperature Coefficient		_	6	_	µV/°C	_
Input Bias Current	I _B	—	10	_	pА	—
Input Offset Current	I _{OS}	—	5	_	pА	—
Input Voltage Range (from V–)	V _{CM}	1	1.8		V	CMRR > 60 dB
Common-Mode Rejection Ratio	CMRR	65	83	_	dB	0V < V _{CM} < 1.35V
Power Supply Rejection Ratio	PSRR	60	85	_	dB	Supply voltage change of 2.7V to 3V
		65	77			$R_L = 5 k\Omega, V_{OUT} = 2 V_{PP}$
arge-Signal A	A _{VOL}	80	90		dB	R _L = 100 kΩ, V _{OUT} = 2 V _{PP}
Voltage Gain		90	101	_		R _L = 500 kΩ, V _{OUT} = 2 V _{PP}
Gain-Bandwidth Product	GBW	_	2.3	_	MHz	R_L = 20 kΩ, C_L = 2 pF, A_V = 11
Phase Margin	PM	_	50	_	0	R_L = 20 kΩ, C_L = 2 pF, A_V = 11
–3 dB Bandwidth	BW	_	4.2		MHz	$R_L = 1 M\Omega, C_L = 2 pF, A_V = 1$
Slew Rate	SR	_	3		V/µs	R_L = 1 MΩ, C_L = 2 pF, A_V = 1, Positive Slew Rate = 1.5 V/µs
Short-Circuit Output Current	t .	4.5	6.3	_		Source
	I _{SC}	4.5	6.2	—	- mA	Sink
Supply Current (per Op Amp)	۱ _S	—	28	45	μA	No Load
Channel-to- Channel Crosstalk	—		-120	_	dB	Note 1

Note 1: DC signal referenced to input. Refer to the Typical Performance Curves section's AC performance graphs.

TABLE 1-3: ELECTRICAL CHARACTERISTICS

Electrical Characteristics: V+ = +5V, V- = 0V, V_{CM} = V+/2; R_L = 500 k Ω to V+/2; -40°C ≤ T_A ≤ +85°C unless otherwise noted.

otherwise noted.				. –		
Parameters	Symbol	Min.	Тур.	Max.	Units	Conditions
		-6	0.1	6		—
Input Offset Voltage		-5	0.1	5	mV	T _A = +25°C
Differential Offset Voltage	V _{OS}	_	0.5	—	mV	—
Input Offset Voltage Temperature Coefficient		_	6	_	μV/°C	_
Input Bias Current	I _B	_	10	—	pА	_
Input Offset Current	I _{OS}	—	5		pА	—
Input Voltage Range (from V–)	V _{CM}	3.5	4.1	—	V	CMRR > 60 dB
Common-Mode Rejection Ratio	CMRR	60	87	—	dB	0V < V _{CM} < 3.5V
Power Supply Rejection Ratio	PSRR	60	92	—	dB	Supply voltage change of 3V to 5V
		65	73	—		$R_L = 5 \text{ k}\Omega, V_{OUT} = 4.8 V_{PP}$
Large-Signal Voltage Range	A _{VOL}	80	86	—	dB	R _L = 100 kΩ, V _{OUT} = 4.8 V _{PP}
voltage i talige		89	96	—		R_{L} = 500 kΩ, V_{OUT} = 4.8 V_{PP}
Maximum Output		V+ – 50 mV	V+ – 37 mV	—	V	R _L = 5 kΩ
Voltage Swing	M	V+ – 3 mV	V+ – 1.3 mV	—		R _L = 500 kΩ
/inimum Output	V _{OUT}	_	V– + 24 mV	V– + 40 mV	v	R _L = 5 kΩ
Voltage Swing		_	V– + 0.7 mV	V– + 3 mV		R _L = 500 kΩ
Gain-Bandwidth Product	GBW	_	3	—	MHz	$R_L = 20 \text{ k}\Omega, C_L = 2 \text{ pF}, A_V = 11$
Phase Margin	PM	—	45	_	0	—
–3 dB Bandwidth	BW	_	5	—	MHz	$R_L = 1 M\Omega, C_L = 2 pF, A_V = 1$
Slew Rate	SR	_	4	_	V/µs	$R_L = 1 M\Omega$, $C_L = 2 pF$, $A_V = 1$, Positive Slew Rate = 1.5 V/µs
Short-Circuit Output		17	23		~^^	Source
Current	I _{SC}	18	27	—	mA	Sink
Supply Current (per Op Amp)	۱ _S	_	31	47	μA	No Load
Channel-to- Channel Crosstalk	_	_	-120	_	dB	Note 1

Note 1: DC signal referenced to input. Refer to the Typical Performance Curves section's AC performance graphs.

TEMPERATURE SPECIFICATIONS (Note 1)

	-		•				
Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions	
Temperature Ranges							
Operating Temperature Range		-40		+125	°C	—	
Storage Temperature Range	Τ _S			+150	°C	—	
Ambient Temperature Range	T _A	-40	_	+85	°C	—	
Package Thermal Resistance							
Thermal Resistance SOT-23-8	θ_{JA}		100	_	°C/W	Using 4-Layer PCB	
	θ _{JC}		70	_	°C/W	Using 4-Layer PCB	

Note 1: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air (i.e., T_A, T_J, θ_{JA}). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +125°C rating. Sustained junction temperatures above +125°C can impact the device reliability.

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2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

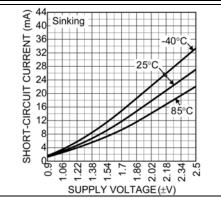


FIGURE 2-1: Short-Circuit Current vs. Supply Voltage.

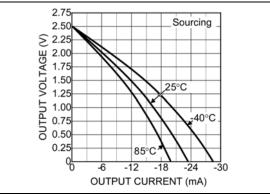
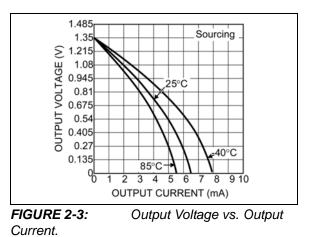
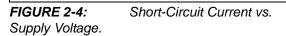


FIGURE 2-2: Output Voltage vs. Output Current.



33 (mA) Sourcing 30 40°Ċ SHORT-CIRCUIT CURRENT 27 24 25°C 21 18 15 85°C 12 Ø, 1.86 2.02 2.18 8 .38 .54 1.7 2.34 2 ö SUPPLY VOLTAGE (±V)



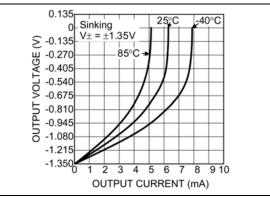


FIGURE 2-5: Output Voltage vs. Output Current.

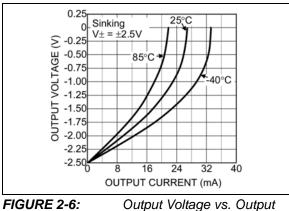


FIGURE 2-6: Output Voltage vs Current.

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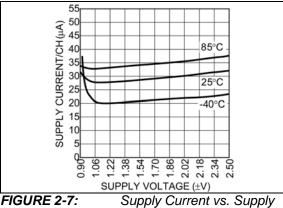


FIGURE 2-7: Voltage.

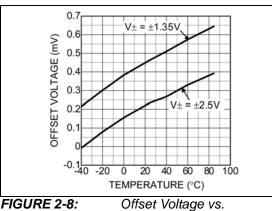


FIGURE 2-8: Temperature.

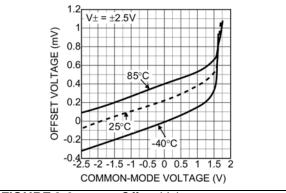


FIGURE 2-9: Offset Voltage vs. Common-Mode Voltage.

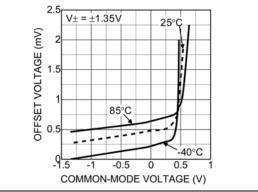


FIGURE 2-10: Offset Voltage vs. Common-Mode Voltage.

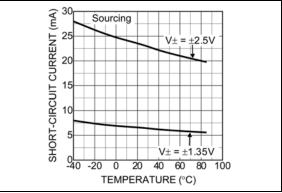
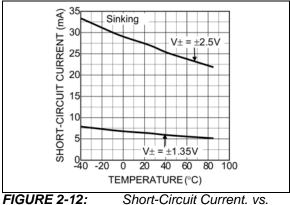


FIGURE 2-11: Short-Circuit Current vs. Temperature.



Temperature.

Short-Circuit Current. vs.

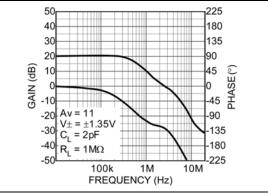


FIGURE 2-13: Gain Bandwidth and Phase Margin.

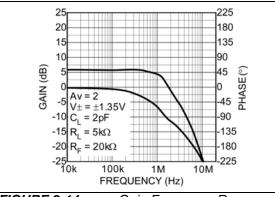


FIGURE 2-14:

Gain Frequency Response.

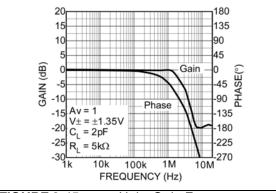


FIGURE 2-15: Unity Gain Frequency Response.

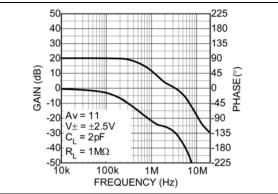


FIGURE 2-16: Gain Bandwidth and Phase Margin.

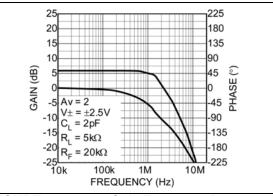


FIGURE 2-17:

Gain Frequency Response.

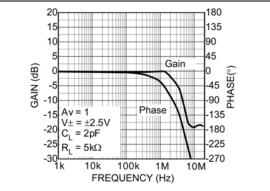


FIGURE 2-18: Unity Gain Frequency Response.

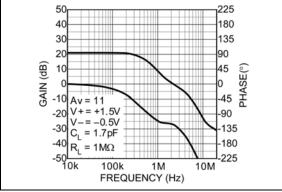
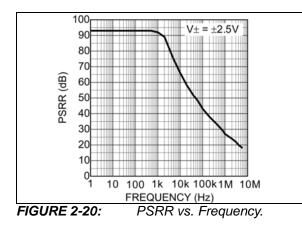


FIGURE 2-19: Gain Bandwidth and Phase Margin.



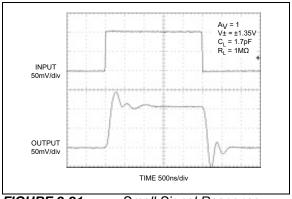
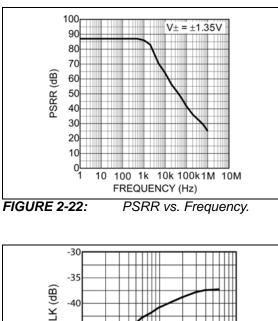


FIGURE 2-21:

Small Signal Response.



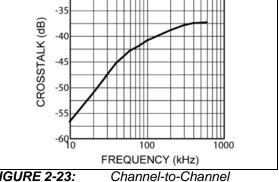
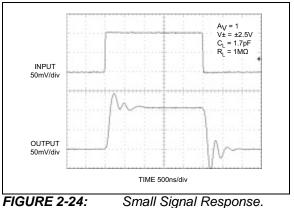
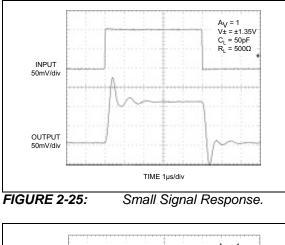
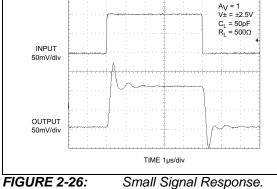


FIGURE 2-23: Crosstalk.



Small Signal Response.





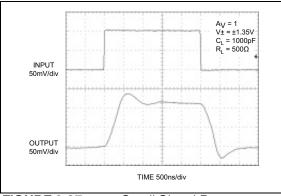


FIGURE 2-27:

Small Signal Response.

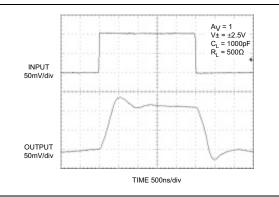


FIGURE 2-28:

Small Signal Response.

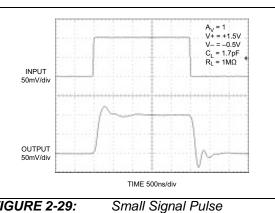


FIGURE 2-29: Response.

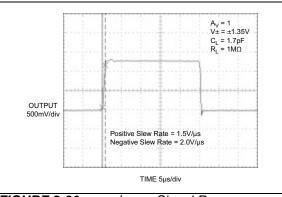


FIGURE 2-30: Large Signal Response.

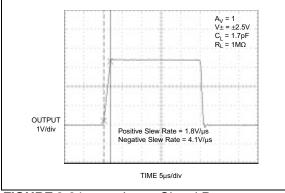
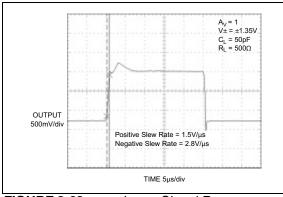


FIGURE 2-31:

Large Signal Response.





Large Signal Response.

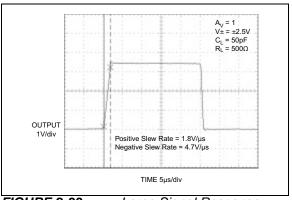


FIGURE 2-33:

Large Signal Response.

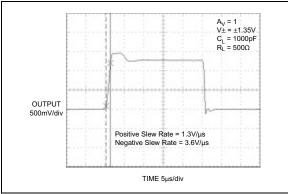


FIGURE 2-34: Large Signal Pulse Response.

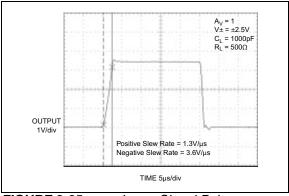
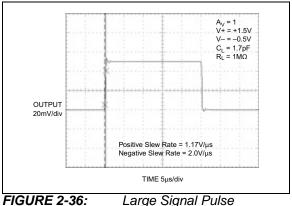


FIGURE 2-35: Response.

Large Signal Pulse



Response.

Large Signal Pulse

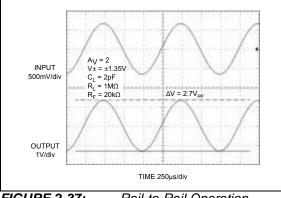


FIGURE 2-37: Rail-to-Rail Operation.

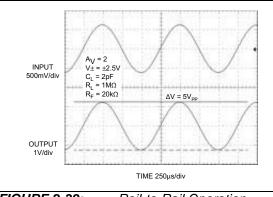


FIGURE 2-38:

Rail-to-Rail Operation.

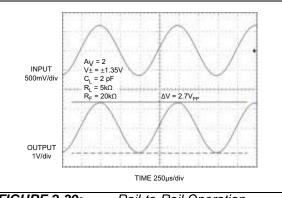


FIGURE 2-39:

Rail-to-Rail Operation.

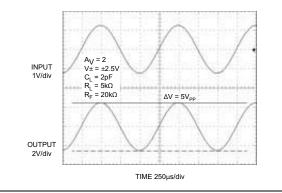


FIGURE 2-40: Rail-to-Rail Operation.

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

Pin Number	Symbol	Description
1	OUTA	Amplifier A Output.
2	INA-	Amplifier A Inverting Input.
3	INA+	Amplifier A Non-Inverting Input
4	V–	Negative Supply.
5	INB+	Amplifier B Non-Inverting Input.
6	INB-	Amplifier B Inverting Input.
7	OUTB	Amplifier B Output.
8	V+	Positive Supply.

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4.0 APPLICATION INFORMATION

4.1 Power Supply Bypassing

Regular supply bypassing techniques are recommended. A 10 μ F capacitor in parallel with a 0.1 μ F capacitor on both the positive and negative supplies are ideal. For best performance all bypassing capacitors should be located as close to the op amp as possible and all capacitors should be low ESL (equivalent series inductance), ESR (equivalent series resistance). Surface-mount ceramic capacitors are ideal.

4.2 Supply and Loading Resistive Considerations

The MIC862 is intended for single-supply applications configured with a grounded load. It is not advisable to operate the MIC862 under either of the following conditions:

- A grounded load and split supplies (±V)
- A single supply where the load is terminated above ground.

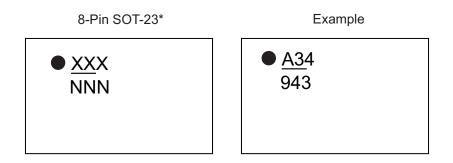
Under the above conditions, if the load is less than 20 k Ω and the output swing is greater than 1V (peak), there may be some instability when the output is sinking current.

4.3 Capacitive Load

When driving a large capacitive load, a resistor of 500Ω is recommended to be connected between the op amp output and the capacitive load to avoid oscillation.

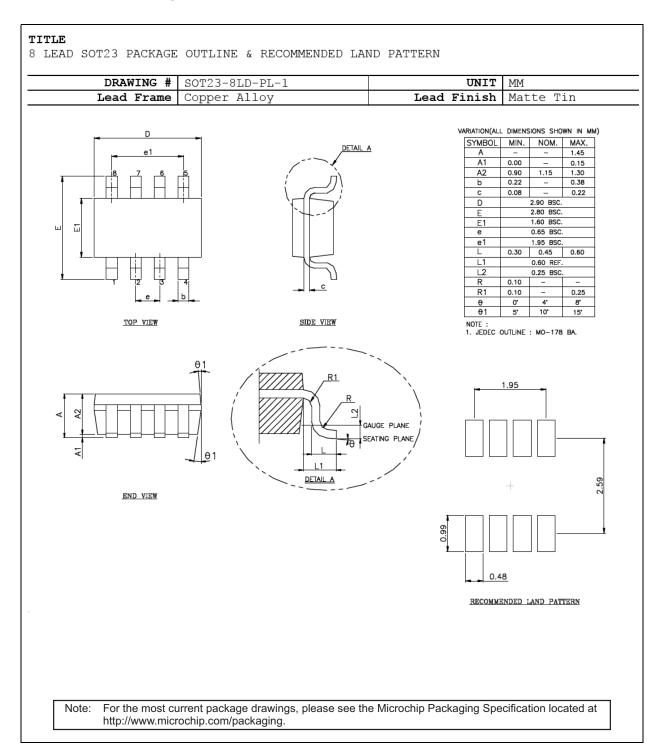
5.0 PACKAGING INFORMATION

5.1 Package Marking Information



Legend:	Y YY WW NNN @3 *	Product code or customer-specific information Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code Pb-free JEDEC [®] designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.
t t	be carried characters the corpor	nt the full Microchip part number cannot be marked on one line, it will d over to the next line, thus limiting the number of available of or customer-specific information. Package may or may not include ate logo. (_) and/or Overbar (⁻) symbol may not be to scale.

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8-Lead SOT-23 Package Outline and Recommended Land Pattern

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APPENDIX A: REVISION HISTORY

Revision A (August 2017)

- Converted Micrel document MIC862 to Microchip data sheet template DS20005836A.
- Minor text changes throughout.
- Corrected the Product Identification System section by removing an errorneous letter T from the part number.

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MIC862

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

		Examples:
	T NO. X -XX vice Temperature Package Media Type MIC862: Dual Ultra-Low Power Op Amp	a) MIC862YM8-TR: Dual Ultra-Low Power Op Amp, -40°C to +85°C Junction Temperature Range, 8-Lead SOT-23 Package, 3,000/Reel
Temperature:	$Y = -40^{\circ}C \text{ to } +85^{\circ}C$	Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on
Package:	M8 = 8-Lead SOT-23	the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.
Media Type:	TR = 3,000/Reel	

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MIC862

NOTES:

Note the following details of the code protection feature on Microchip devices:

- · Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
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